

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Masaru SHIRAI et al.

Confirmation No. 1550

Serial No.: 10/598,142

Group Art Unit: 1793

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Examiner: Nicholas P D'ANIELLO

For: **HEATER, REFLOW APPARATUS, AND SOLDER BUMP FORMING METHOD  
AND APPARATUS**

United States Patent and Trademark Office  
Customer Service Window, Mail Stop Amendment  
Randolph Building  
401 Dulany Street  
Alexandria, VA 22314

**REQUEST FOR EXTENSION OF TIME**

Sir:

Please extend the time for response to the Official Action dated October 13, 2009 by one month from January 13, 2010 to February 16, 2010 (February 13, 2010 being a Saturday and February 15, 2010 being a federal holiday). The amount of \$130.00 is submitted concurrently herewith as payment for the fee.

The U.S. Patent and Trademark Office is hereby authorized to credit any overpayment or charge any additional fee to Deposit Account No.19-0089.

Respectfully submitted,  
Masaru SHIRAI et al.

  
Bruce H. Bernstein  
Reg. No. 29027

GREENBLUM & BERNSTEIN, P.L.C.  
1950 Roland Clarke Place  
Reston, VA 20191  
(703) 716-1191